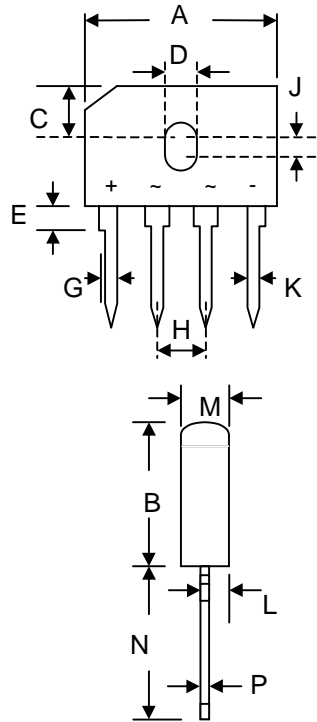


## 4.0A GLASS PASSIVATED BRIDGE RECTIFIER

### Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards



Dim	GBU	
	Min	Max
A	21.80	22.30
B	18.30	18.80
C	7.40	7.90
D	3.50	4.10
E	1.52	2.03
G	2.16	2.54
H	4.83	5.33
J	1.65	2.16
K	1.65	2.03
L	0.76	1.02
M	3.30	3.56
N	17.50	18.00
P	0.46	0.56
All Dimensions in mm		

### Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 4.0 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	GBU4A	GBU4B	GBU4D	GBU4G	GBU4J	GBU4K	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	50	100	200	400	600	800	V
RMS Reverse Voltage	V <sub>R(RMS)}</sub>	35	70	140	280	420	560	V
Average Rectified Output Current @T <sub>C</sub> = 100°C @T <sub>A</sub> = 40°C	I <sub>O</sub>	4.0 3.0						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	150						A
I <sup>2</sup> t Rating for Fusing (t < 8.35ms)	I <sup>2</sup> t	93						A <sup>2</sup> s
Forward Voltage (per element) @I <sub>F</sub> = 4.0A	V <sub>FM</sub>	1.0						V
Peak Reverse Current At Rated DC Blocking Voltage @T <sub>A</sub> = 25°C @T <sub>C</sub> = 100°C	I <sub>R</sub>	5.0 500						μA
Typical Thermal Resistance (per leg) (Note 1)	R <sub>θJA</sub>	19						K/W
Typical Thermal Resistance (per leg) (Note 2)	R <sub>θJC</sub>	4.0						K/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150						°C

Note: 1. Thermal resistance junction to ambient, mounted on PCB at 9.5mm lead length with 12mm<sup>2</sup> copper pads.  
2. Thermal resistance junction to case, mounted on 5.0 x 4.0 x 0.8cm thick AL plate.

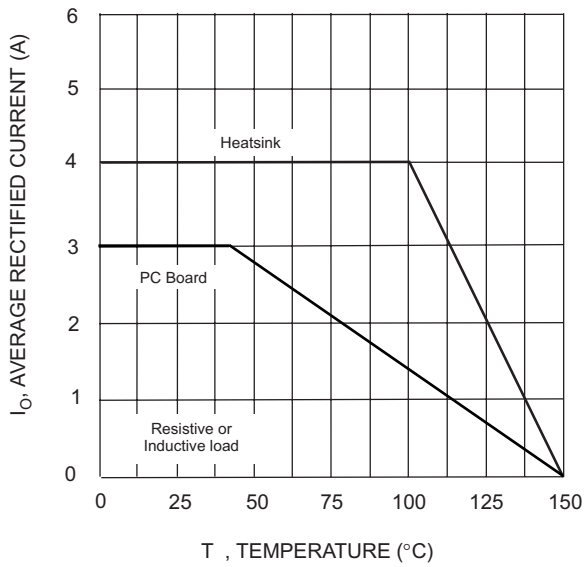


Fig. 1 Forward Current Derating Curve

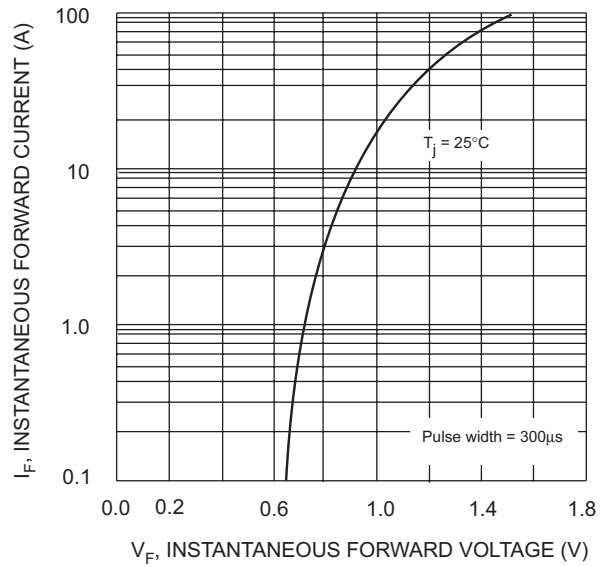


Fig. 2 Typical Fwd Characteristics, per element

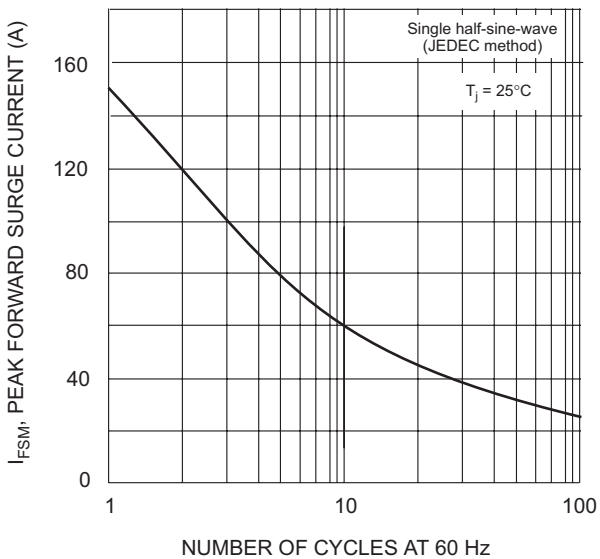


Fig. 3 Maximum Non-Repetitive Surge Current

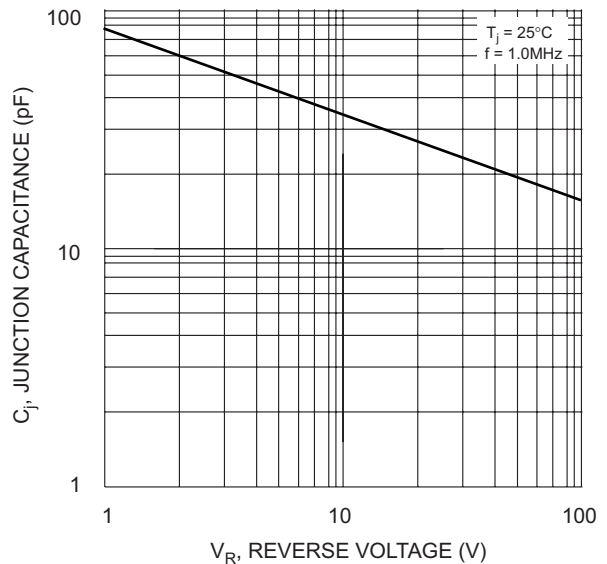


Fig. 4 Typical Junction Capacitance

## ORDERING INFORMATION

Product No.	Package Type	Shipping Quantity
GBU4A	SIL Bridge	25 Units/Tube
GBU4B	SIL Bridge	25 Units/Tube
GBU4D	SIL Bridge	25 Units/Tube
GBU4G	SIL Bridge	25 Units/Tube
GBU4J	SIL Bridge	25 Units/Tube
GBU4K	SIL Bridge	25 Units/Tube

Shipping quantity given is for minimum packing quantity only. For minimum order quantity, please consult the Sales Department.

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**WARNING:** DO NOT USE IN LIFE SUPPORT EQUIPMENT. WTE power semiconductor products are not authorized for use as critical components in life support devices or systems without the express written approval.

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